



3.3 Electrical Specifications

3.3.1 Maximum Ratings

Storage temperature	-40 to +125° C
Operating free-air temperature range	0 to +70° C
Supply voltage applied to ground potential	-0.5 to +7.0 V
DC voltage applied to outputs for high output state	-0.5 to Vdd max.
DC input voltage	+4.75V to +5.25 V
Supply current	200mA typ / 300 max.
Analog output current	45mA
Reference current	-15mA



3.3.2 Electrical Characteristics

The following condition applies unless otherwise specified: T(A) = 0 + 70° Vdd = 5.0 V ±5%

DC Characteristics Over Operating Temperature							
Symbol	Parameter	I/O Cell	Condition	Min.	Typ.	Max.	Unit
V _{IH}	High Level Input Voltage	TTL		2.0			V
		CMOS		3.5			
		CMOS Schmidt trigger		4.0			
V _{IL}	Low Level Input Voltage	TTL				0.8	V
		CMOS				1.5	
		CMOS Schmidt trigger				1.0	
I _{IH}	High Level Output Current	Input buffer	V _{IN} =VCC	-10		10	uA
		Input buffer with pull-down		10		200	
I _{IL}	Low Level Output Current	Input buffer	V _{IN} =GND	-10		10	uA
		Input buffer with pull-up		-200		-10	
V _{OH}	High Level Output Voltage	BT2, BD2 TTL	I _{OH} =-2mA	2.4			V
		BT4, BT4 TTL	I _{OH} =-4mA				
		BT8, BD8 TTL	I _{OH} =-8mA				
		BTPCI, BDPCI TTL	I _{OH} =-2mA	2.4			
		ALL TTL	I _{OH} =-1uA	VCC-0.05			
		BT4, BD4 CMOS	I _{OH} =-4mA	3.5			
V _{OL}	Low Level Output Voltage	BT2, BD2 TTL	I _{OL} =2mA			0.5	V
		BT4, BT4 TTL	I _{OL} =4mA				
		BT8, BD8 TTL	I _{OL} =8mA				
		BTPCI, BDPCI TTL	I _{OL} =6mA		0.55		
		ALL TTL	I _{OL} =1uA		0.05		
		BT4, BD4 CMOS	I _{OL} =4mA		1.5		
I _{oz}	High Impedance Leakage current	Output buffer	V _{OUT} =VCC or GND	-10		10	uA
		Output buffer with pull-up		-200		-10	
		Output buffer with pull-down		10		200	
V _H	Schmidt Trigger Hysteresis Voltage				0.6		V

NOTE: The MDRAM outputs (see pins below) are specifically designed to work into 220Ω loads, to VDD and ground, with reduced swing and a 50 percent duty cycle to achieve the high data exchange rate. Different loads may affect performance.

MDRAM Outputs	
Pins	Function
MD1<15:0>, MD0<15:0>	input/output
MM1<1:0>, MM0<1:0>	input to MDRAM
CLK1, CLK0	input to MDRAM



3.3.3 DAC Characteristics

Symbol	Parameter	Conditions	Min.	Max.	Units
V_{REF}	Reference voltage		1.10	1.35	V
V_O (max)	Maximum output voltage	$I_O \leq 10\text{mA}$		1.5	V
I_O (max)	Maximum output current	$V_O \leq 1\text{V}$		21	mA
	Full scale error	note A, B		± 5	%
	DAC to DAC correlation	note B		± 2	%
	Integral linearity, 6-bit	note B		± 0.5	LSB
	Integral linearity, 8-bit	note B		± 1	LSB
	Full-scale settling time*, 6-bit	note C		28	ns
	Full-scale settling time*, 8-bit	note C		20	ns
	Rise time (10% to 90%)*	note C		6	ns
	Glitch energy*	note C		200	pVsec

* Characterized values only

3.3.4 PLL Characteristics

Symbol	Parameter	Conditions	Min.	Max.	Units
F_D	Frequency change of CLK0 and CLK1 over supply and temperature	With respect to typical frequency		0.05	%
f_0	CLOCK0 operating range*		25	135	MHz
f_1	CLOCK1 operating range*		25	135	MHz
d_t	Duty cycle*		40/60	60/40	%
$j_{1\sigma}$	Jitter, one sigma*			130ps	ps
j_{abs}	Jitter, absolute*		-300ps	300ps	ps
f_{ref}	Input reference frequency	typically 14.318MHz	5	25	MHz

NOTES:

A. Full scale error is derived from design equation

$$\{[(F.S.I_{out})R_L - 2.1(I_{REF})R_L]/[2.1(I_{REF})R_L]\} 100\%$$

$$V_{BLACK LEVEL} = 0V$$

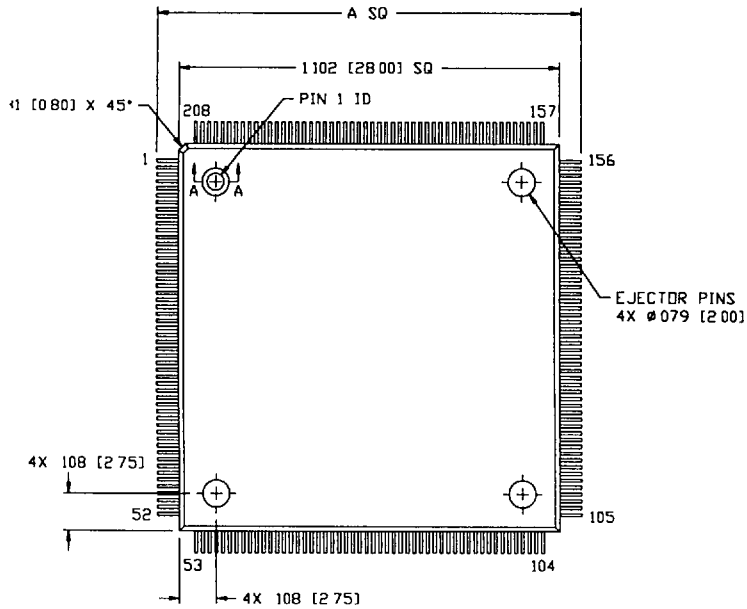
$$F.S.I_{OUT} = \text{Actual full scale measured output}$$

B. $R = 37.5\Omega$, $I_{REF} = -8.88\text{mA}$, $J_{REF} = V_{REF}/R_{SET}$

C. $Z_1 = 37.5\Omega + 30\text{pF}$, $I_{REF} = -8.88\text{mA}$

Appendix C. Mechanical Specification

ET6000 208-pin Plastic Quad Flat Package



006 [0.15] BARE FRAME
007 [0.16] PLATED FRAME

